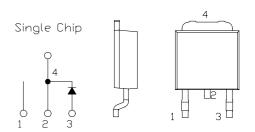
Nihon Inter Electronics Corporation

 $\textbf{SBD} \quad \mathrm{Type} \,:\, EA30QS04\text{-}F$

OUTLINE DRAWING

FEATURES

- * TO-252AA Case, Surface Mounting Device
- * Low Forward Voltage drop
- * Low Power Loss
- * High Surge Capability
- * 40 Volts thru 100 Volts Types Available
- * Packaged in 16mm Tape and Reel



Maximum Ratings

Approx Net Weight:0.30g

Rating		Symbol	EA30QS04-F			Unit
Repetitive Peak Reverse Voltage		V_{RRM}	40			
Non-repetitive Peak Reverse Voltage		V _{RSM}	45			V
Average Rectified Output Current	P.C.Board mounted *	Io	1.8	Ta=24°C	50Hz Half Sine Wave Resistive Load	A
	-		3.0	Tc=131°C	Resistive Load	
RMS Forward Current		I _{F(RMS)}	4.71			
Surge Forward Current		Ifsm	45	45 50Hz Half Sine Wave,1cycle, Non-repetitive		
Operating JunctionTemperature Range		Tjw	- 40 to + 150			°C
Storage Temperature Range		Tstg	- 40 to + 150			

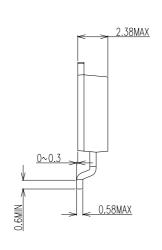
Electrical • Thermal Characteristics

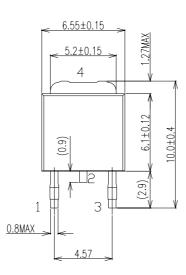
Characteristics		Symbol	Conditions	Min	Тур	Max	Unit
Peak Reverse Current		I_{RM}	Tj=25°C,V _{RM} =V _{RRM}	-	-	2.0	mA
Peak Forward Voltage		V_{FM}	$Tj=25^{\circ}C,I_{FM}=3$ A	-	-	0.55	V
Thermal	Junction to Ambient	Rth(j-a)	P.C.Board mounted *	-	-	80	°C/W
Resistance	Junction to Case	Rth(j-c)	-	=	-	6	°C/W

^{*} Print Land = 20x20 mm

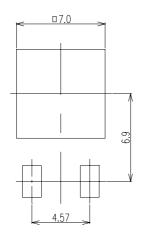
Nihon Inter Electronics Corporation

EA30QS04-F OUTLINE DRAWING (Dimensions in mm)





SOLDERING PAD



Single Chip

